

Product/Process Change Notification

N° 2022-084-A

Dear customer,

please find attached our Infineon Technologies AG PCN:

Introduction of an additional wafer production for top chip and an additional wafer test location for base and top chip at Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia, for product BTS443P

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2023-04-02.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates:
"Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."
Notwithstanding the aforesaid individual agreements shall prevail.

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG

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Chairman of the Supervisory Board Dr. Herbert Diess

Management Board Jochen Hanebeck (CEO), Constanze Hufenbecher, Dr. Sven Schneider, Andreas Urschitz, Dr. Rutger Wijburg

Registered office Neubiberg Commercial register Amtsgericht München HRB 126492

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Products affected

Please refer to attached affected product list PCN_2022-084-A_[customer-no].pdf

Detailed change information

Subject: Introduction of an additional wafer production for top chip and an additional wafer test location for base and top chip at Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia, for product BTS443P

Reason/Motivation: Expansion of wafer production and wafer test to assure continuity of supply and enable flexible manufacturing.

Description	Old	New
PROCESS - WAFER PRODUCTION: Move all or parts of production to a different wafer fab site	Top chip: Infineon Technologies Austria AG, Villach, Austria	Top chip: Infineon Technologies Austria AG, Villach, Austria and Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia
TEST FLOW: Move of all or part of electrical wafer test and/or final test to a different test site	Base and top chip: Infineon Technologies Austria AG, Villach, Austria	Base and top chip: Infineon Technologies Austria AG, Villach, Austria and Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia

Product identification

Traceability assured via date code.
No change in SP ordering number.

Anticipated impact of change

Based on the qualification performed, Infineon does not expect any negative impact on quality, function and reliability. No change in fit, form and function expected.

DeQuMa-ID(s): SEM-PW-13 / SEM-TF-01

Attachments

PCN_2022-084-A_[customer-no].pdf affected product list

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Time schedule

Final qualification report	available
First samples available	on request
Intended start of delivery [1]	2023-08-31
Last order date (LOD) [2]	2023-08-31
Last delivery date (LDD) [3]	2024-08-31

[1] Provided date or earlier after customer approval.

[2] Last date where orders for unchanged products will be accepted.

[3] Last date for delivery of unchanged products. Delivery of changed products can be earlier (see Intended start of delivery) and depends on approval.

If you have any questions, please do not hesitate to contact your local sales office.

BTS443P

SP000264198

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